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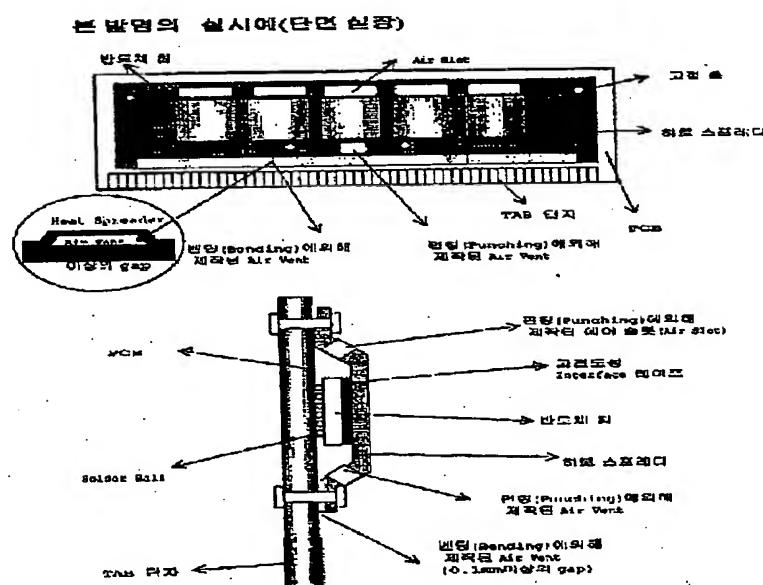
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PACKAGE STRUCTURE WITH HIGH RADIATION HEAT SPREADER FOR COPING WITH THIN FILM SYSTEM AND MANUFACTURING METHOD THEREOF

Representative drawing

(57) Abstract:



PURPOSE: A method is provided to manufacture a package structure with a high radiation heat spreader for coping with a thin film system, by adhering a unit heat sink for improving a thermal characteristic of a high speed semiconductor device at a unit package level.

CONSTITUTION: Powder of SiC or artificial diamond having a high emissivity is placed on a heat spreader and a coating layer of more than 3 micro meter by a low temperature wet plating method. A preprocessed heat sink is stacked on a rear surface of a semiconductor chip by intervening high conductive thermosetting or thermoplasticity adhesion tape or liquid adhesive and by using an align key formed in the heat sink and a substrate. A semiconductor chip pad is electrically connected to

an internal terminal of a package. A molding process is carried out to protect the semiconductor chip from an exterior impact. An exterior electrode is formed by a solder ball or lead. A package of a strip state to which the heat sink is adhered is cut to an individual package.

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